

2025 COOLERCHIPS Annual Review

November 20-21, 2025

**Hilton at the Ballpark
St. Louis, Missouri**

Agenda

Thursday, November 20th, 2025: Salons D, E, F and G

8:00 – 11:30 AM	OPTIONAL: MOSTCOOL TUTORIAL SESSION
11:30 – 1:00 PM	REGISTRATION, LUNCH FROM 12-1 PM
1:00 – 1:20 PM	WELCOME REMARKS AND COOLERCHIPS OVERVIEW Laurent Pilon, Associate Director for Technology, ARPA-E Jungho Kim, Program Director, ARPA-E
1:20 – 1:40 PM	STATE OF THE LIQUID COOLING INDUSTRY Moises Levy, PhD - CEO, DCMETRIX
1:40 – 2:25 PM	INDUSTRY SPEAKERS Meta: Jiu Xiu, Thermal Engineer, Infra Platform Hardware Supermicro: Craig Yamasaki, Senior Director of Product Management Google: Feini Zhang, Thermal Solution Design Engineer
2:25 – 2:35 PM	BREAK
2:35 – 3:50 PM	CATEGORY B, C, AND D PRESENTATIONS NVIDIA, UC Davis, Flexnode, U. of Maryland, NREL
3:50 – 4:05 PM	BREAK
4:05 – 5:40 PM	THE MEGAWATT RACK PANEL DISCUSSION Peter de Bock, Eaton, VP Data Center Energy & Cooling, Moderator Introduction: Jungho Kim, Program Director, ARPA-E Single Phase DTC: Hussam Kabbani, Google Two-Phase DTC: My Truong, Zutacore Single Phase Immersion: Ryan Howard, Submer Two-phase immersion: Bill Murdock, E3NV Microtube Condensers, Kevin Kelly, Mezzo Technologies
5:40 – 5:45 PM	CLOSING REMARKS Jungho Kim, Program Director, ARPA-E
5:45 – 7:30 PM	POSTER SESSION AND REFRESHMENTS Salon C

Friday, November 21st, 2025: Salons D, E, F and G

7:00 – 8:00 AM	BREAKFAST
8:00 – 8:05 AM	WELCOME REMARKS Laurent Pilon, Associate Director for Technology, ARPA-E
8:05 – 8:30 AM	LIQUID COOLING AT SCALE – INTEGRATION AND BUSINESS CONSIDERATIONS Andrea Tsapralis, Director, Solutions Development and Innovation
8:30 – 10:00 AM	CATEGORY A PRESENTATIONS HPI, UT Arlington, U. Missouri, Purdue, U. Illinois Urbana-Champaign, JetCool
10:00 – 10:15 AM	BREAK
10:15 – 11:15 AM	CATEGORY A PRESENTATIONS CONTINUED RTX, Intel, U. Florida, HRL, IBM
11:15 – 11:30 AM	CLOSING REMARKS Jungho Kim, Program Director, ARPA-E